

Sliver for SFF-TA-1002

TE Internal #: 2344604-1

Sliver for SFF-TA-1002, PCB Edge Card, Vertical, Cable-to-Board, Through Hole - Solder, Power, Sliver for SFF-TA-1002, Internal I/O

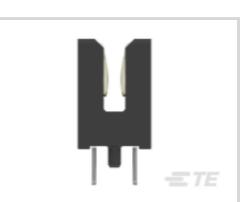
Connectors

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Internal I/O Connector Type: Sliver for SFF-TA-1002

Connector Mates With: PCB Edge Card

PCB Mount Orientation: Vertical
Connector System: Cable-to-Board

Industry Standard: Gen-Z

Features

Mechanical Attachment

Connector Mounting Type	Board Mount
Usage Conditions	
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
Contact Features	
PCB Contact Termination Area Plating Material	Tin
Contact Underplating Material	Nickel
Contact Mating Area Plating Material	Gold
Contact Base Material	Copper Alloy
Contact Current Rating (Max)	55 A
Contact Mating Area Plating Material Thickness	.381 μm[15 μin]
Configuration Features	
Number of Rows	2
PCB Mount Orientation	Vertical



Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Internal I/O Connector Type	Sliver for SFF-TA-1002
Connector Mates With	PCB Edge Card
Connector System	Cable-to-Board
Termination Features	
Termination Method to PCB	Through Hole - Solder
Operation/Application	
Circuit Application	Power
Industry Standards	
Industry Standard	Gen-Z

Compliant

Compliant

Product Compliance

EU RoHS Compliance

EU ELV Compliance

Other

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

Product Compliance Disclaimer

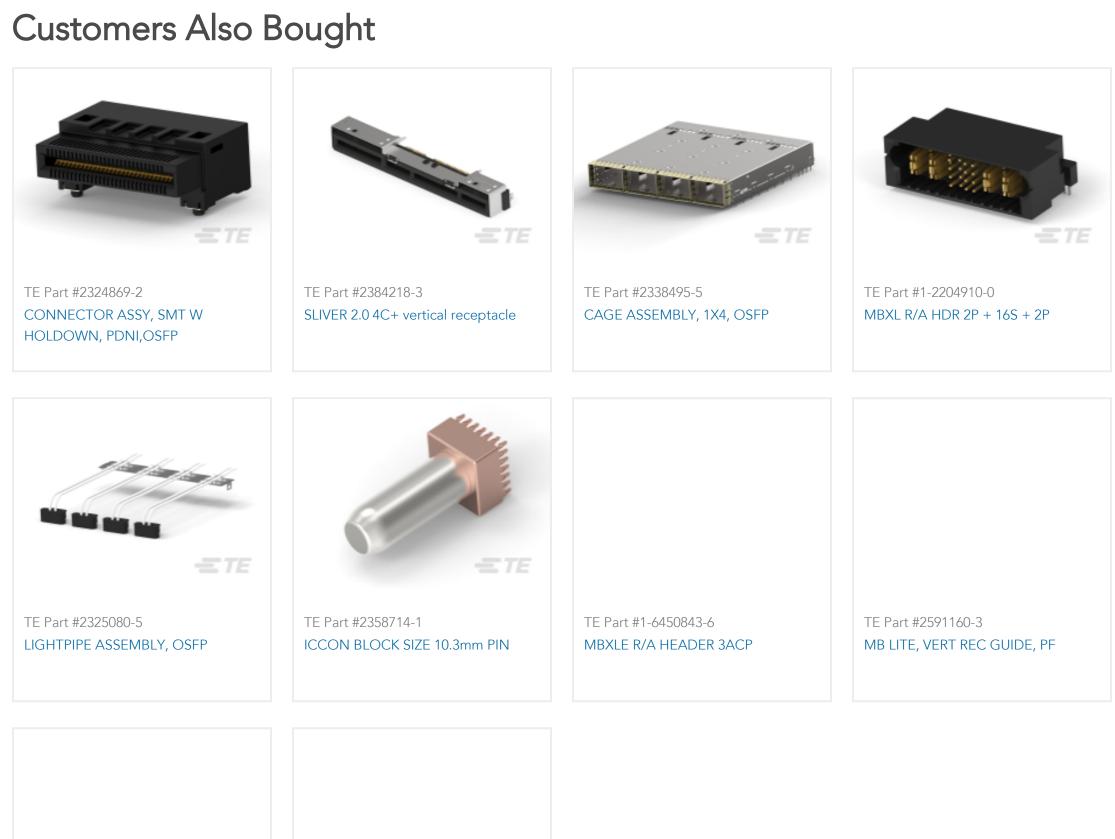
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits



as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Also in the Series | Sliver for SFF-TA-1002





TE Part #2468000-2 MULTI-BEAM HEIGHT TE Part #2468000-1 MULTI-BEAM HEIGHT

Documents

CAD Files
3D PDF



3D

Customer View Model

ENG_CVM_CVM_2344604-1_1.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2344604-1_1.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2344604-1_1.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

Sliver Internal Cabled Interconnect Solutions Brochure (Chinese)

Product Specifications

Application Specification

English